

Description: 1.575 GHz GNSS Ceramic Chip Antenna

PART NUMBER: W3011

Features:

- Frequency 1559-1606.6MHz
- Gain 1 / 1.8 / 1.4dBi
- Size 3.2 x 1.6 x 1.1 mm
- PCB Keep out 4 x 4.25 mm
- Polarization Linear
- Radiation pattern Omni

Applications:

- L1 GNSS Receivers
- Beidou, GPS, Galileo Glonass
- IoT, M2M
- Asset tracking
- Portable satellite receivers

Series: Ceramic Chip Antenna

All dimensions are in mm / inches

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ELECTRICAL SPECIFICATIONS

Antenna Type	Chip antenna
Frequency	1559-1563MHz
	1574.4-1576.4MHz
	1598.6-1606.6MHz
Nominal Impedance	50 Ω
Return Loss (Max)	-6 / -10 / -7 dB
Radiation Pattern	Omni
Gain(Min)	1 / 1.8 / 1.4dBi
Efficiency(Min)	50 / 68 / 60 %
Polarization	Vertical
Power Withstanding	2W

MECHANICAL SPECIFICATIONS

Compact size	3.2 x 1.6 x 1.1mm
Weight	0.033g
Fixing system	SMT
MSL(MOISTURE SENSITIVITY LEVEL)	1

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature Storage Temperature RoHS Compliant -40 ~ +85° C -40 ~ +85° C Yes

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2

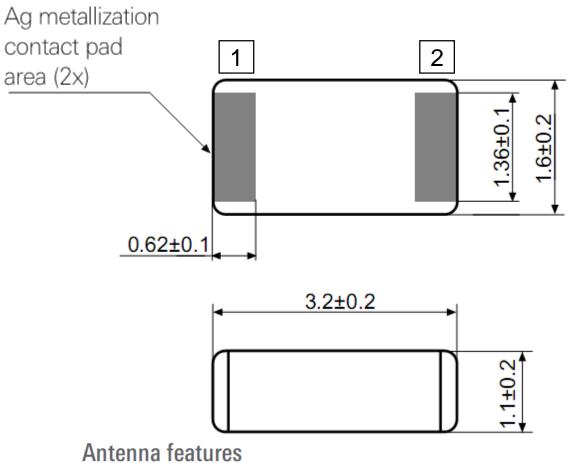


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MECHANICAL DRAWING



No.	Terminal name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm

Antenna is symmetrical.

Either of terminals 1 or 2 can be feed / GND

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3



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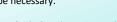
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W3011 GPS Antenna PWB Layout

Ground cleared under antenna, clearance area 4.00 x 4.25 mm Matching and tuning component value and placement depend on application and surrounding mechanics / materials.

Feed line should be designed to match 50 Ω characteristic impedance, depending on PWB material and thickness. Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37 mm.







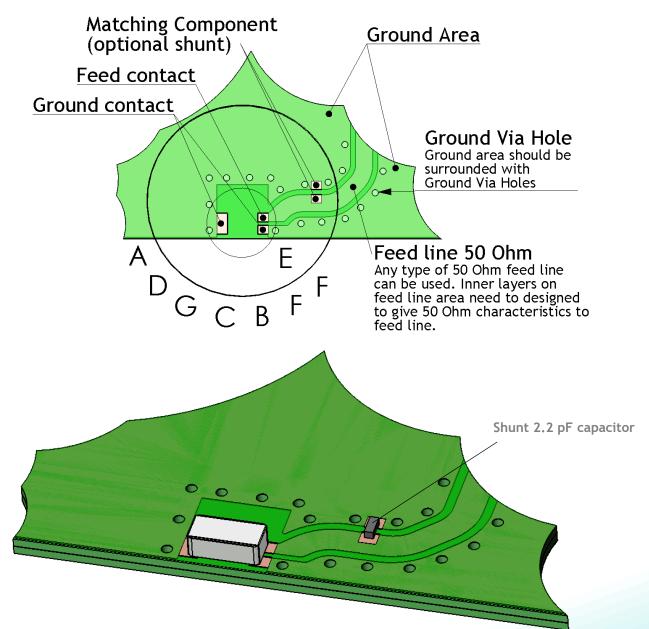
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PWB layout for W3011 GPS Antenna

Note: All dimensions are in metric system.



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5



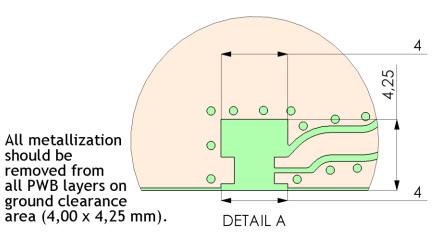
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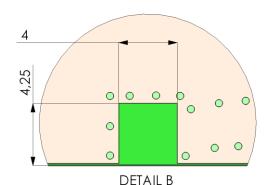
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Ground clearance area for W3011 GPS Antenna

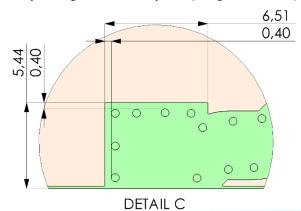
Ground clearance area (4,00 x 4,25 mm)



Opening in bottom/inner ground layers



Opening in other layers (no ground/ RF)



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6

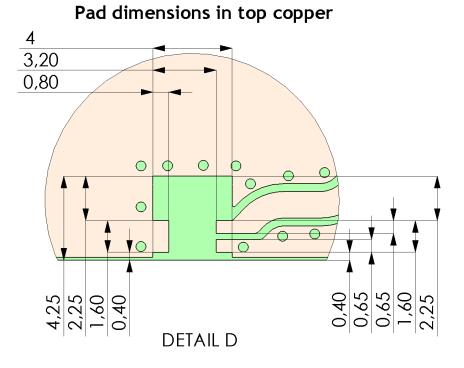


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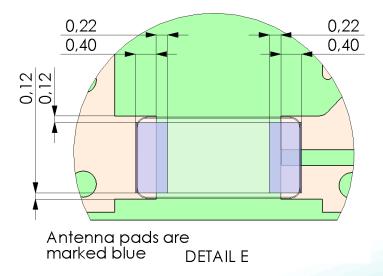
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PWB pad dimensions and antenna position for W3011 GPS Antenna



Antenna position on PWB layout



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7

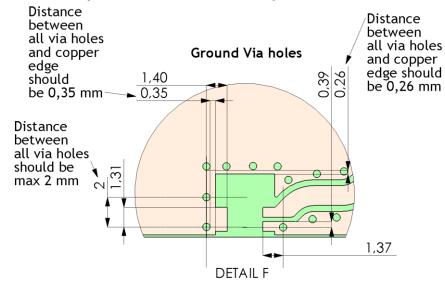


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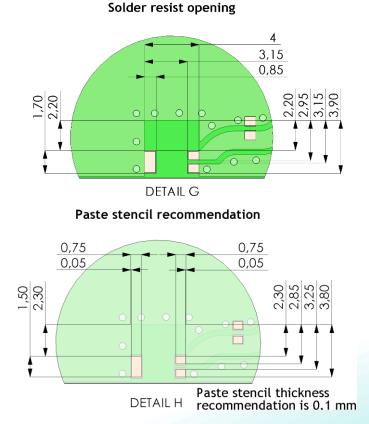
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Typical Ground via hole placement in PWB layout for W3011 GPS Antenna



Solder resist opening and paste stencil recommendations for W3011 GPS Antenna



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8



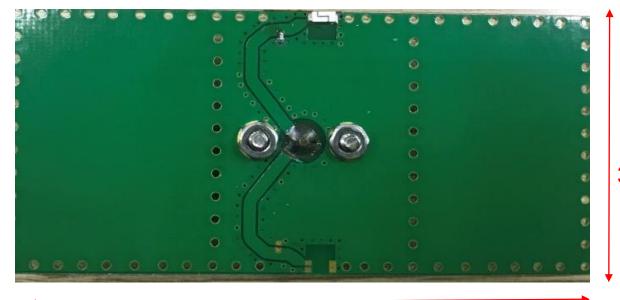
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TEST SETUP

All RF parameters tested on 80x37mm sized test board. Antenna position on side center of PCB long edge.



37mm

80mm

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9



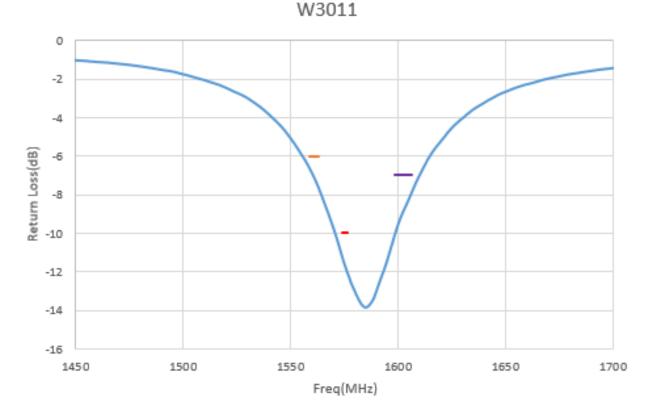
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CHARTS

Return Loss vs Frequency



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ROHS 10



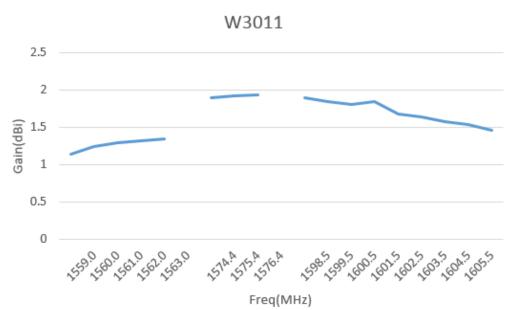
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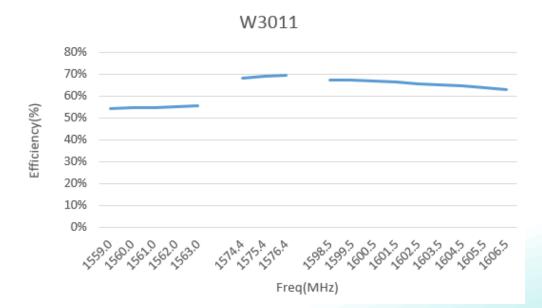
CHARTS

PART NUMBER: W3011

Gain vs Frequency



Radiation Efficiency vs Frequency



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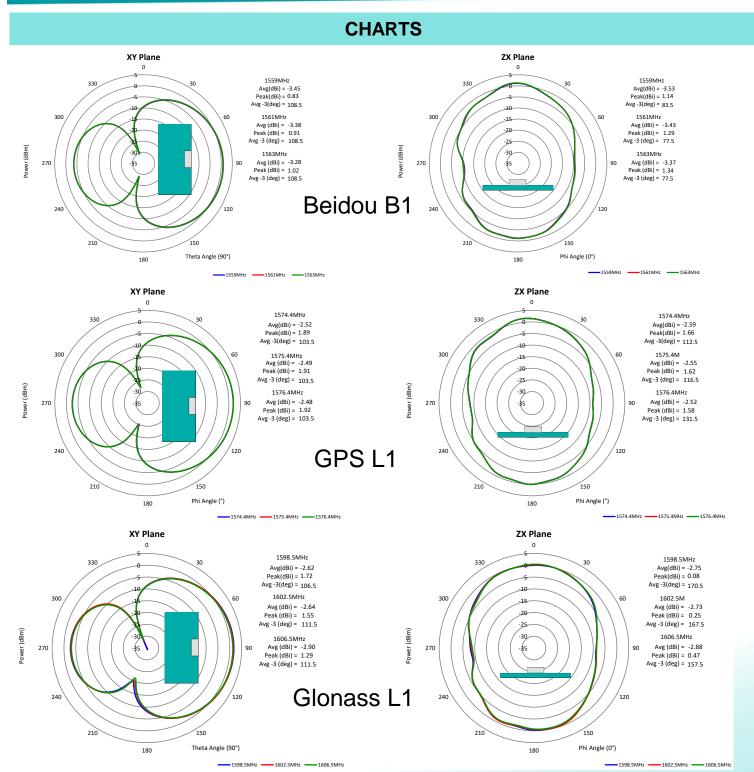
11



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12

RóHS



Series: Ceramic Chip Antenna

TECHNICAL DATA SHEET

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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection	
1	Average temperature gradient in preheating	2.5 °C/s	
2	Soak time	2-3 minutes	
3	Max temperature gradient in reflow	3 °C/s	
4	Time above 217 °C	Max 30 sec	
5	Peak temperature in reflow	230 °C for 10 seconds	
6	Temperature gradient in cooling	Max -5 °C/s	

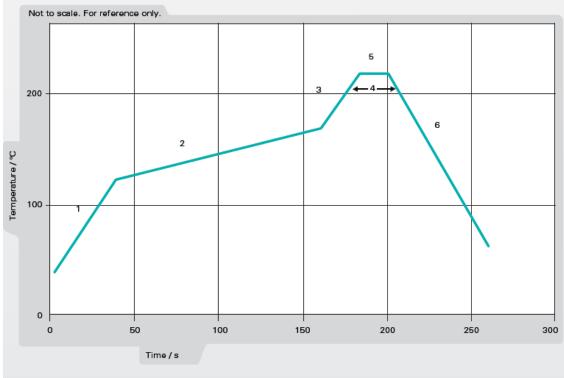


Figure 1. Minimum temperature profile recommendation for reflow soldering process

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Recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection	
1	Average temperature gradient in preheating	2.5 °C/s	
2	Soak time	2-3 minutes	
3	Max temperature gradient in reflow	3 °C/s	
4	Time above 217 °C	Max 60 sec	
5	Time above 230 °C	Max 50 sec	
6	Time above 250 °C	Max 10 sec	
7	Peak temperature in reflow	260 ℃ for 5 seconds	
8	Temperature gradient in cooling	Max -5 °C/s	

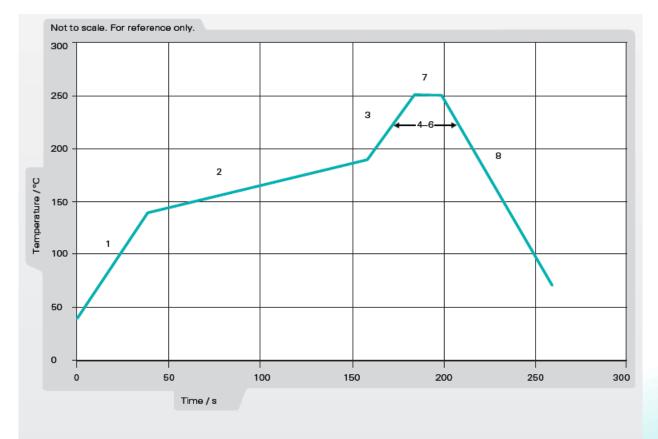


Figure 2. Maximum temperature profile recommendation for reflow soldering process

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14

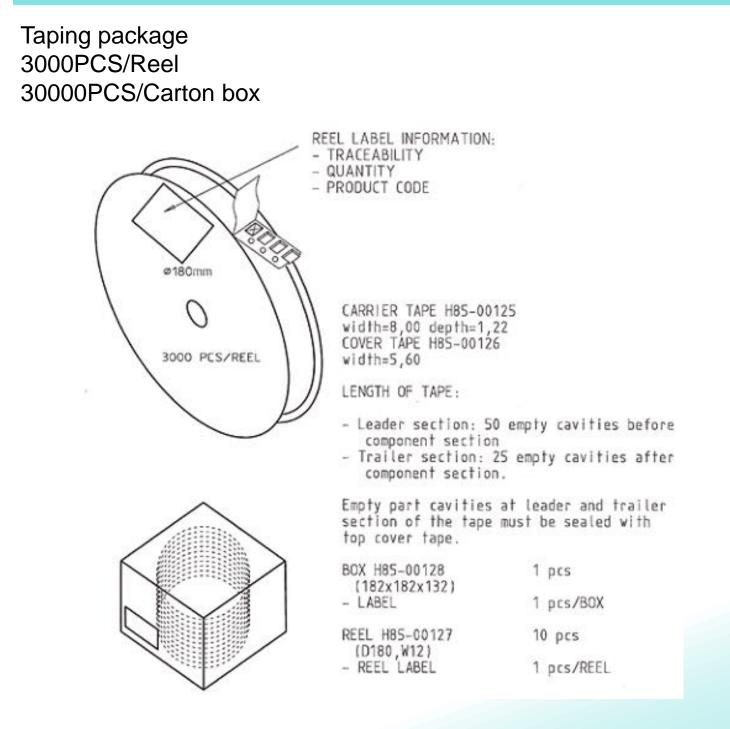


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PART NUMBER: W3011

PACKAGING



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15

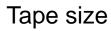


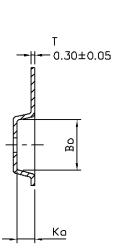
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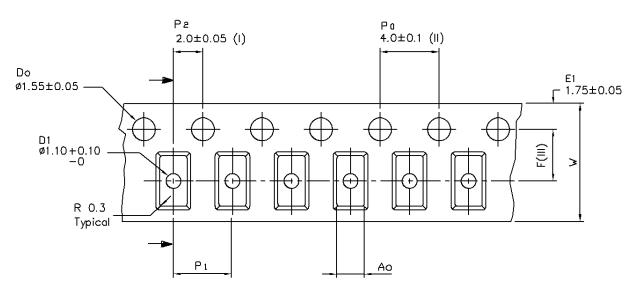
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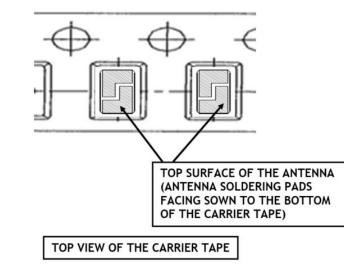
PACKAGING







Ao	1.85	+/- 0.1
Bo	3.43	+/- 0.1
Ко	1.22	+/- 0.1
F	3.50	+/- 0.05
Ρ1	4.00	+/- 0.1
W	8.00	+/- 0.1



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